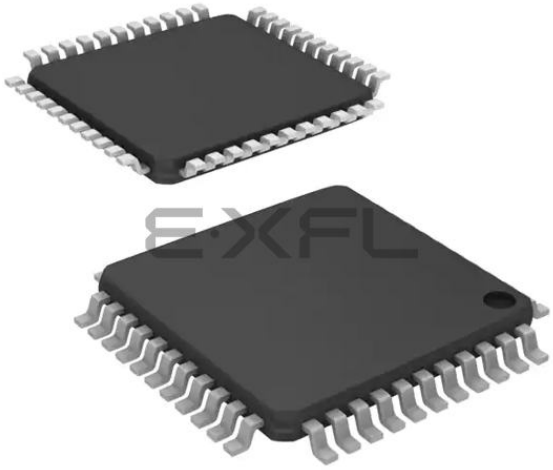

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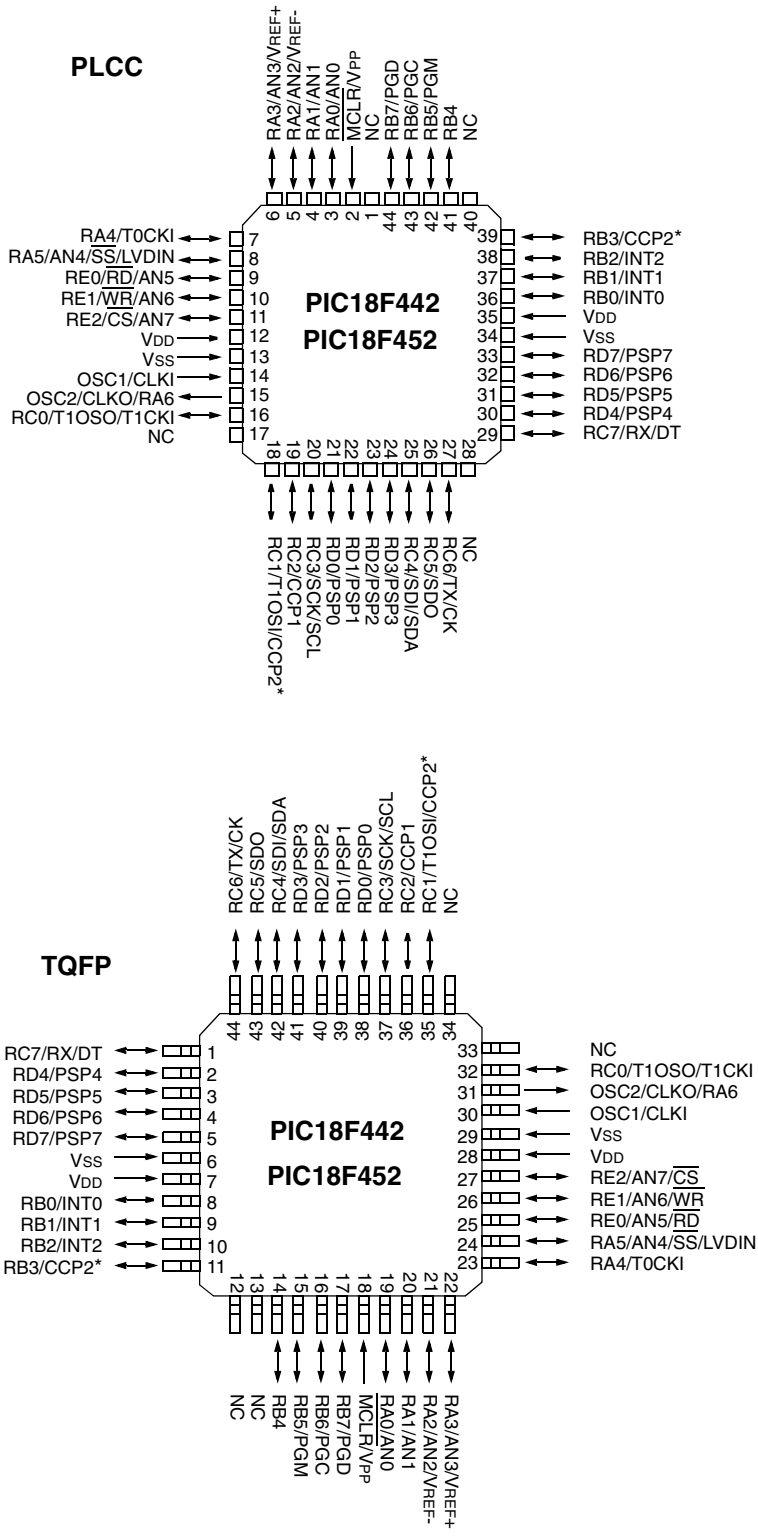
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f452-i-pt

Pin Diagrams



* RB3 is the alternate pin for the CCP2 pin multiplexing.

2.0 OSCILLATOR CONFIGURATIONS

2.1 Oscillator Types

The PIC18FXX2 can be operated in eight different Oscillator modes. The user can program three configuration bits (FOSC2, FOSC1, and FOSC0) to select one of these eight modes:

1. LP Low Power Crystal
2. XT Crystal/Resonator
3. HS High Speed Crystal/Resonator
4. HS + PLL High Speed Crystal/Resonator with PLL enabled
5. RC External Resistor/Capacitor
6. RCIO External Resistor/Capacitor with I/O pin enabled
7. EC External Clock
8. ECIO External Clock with I/O pin enabled

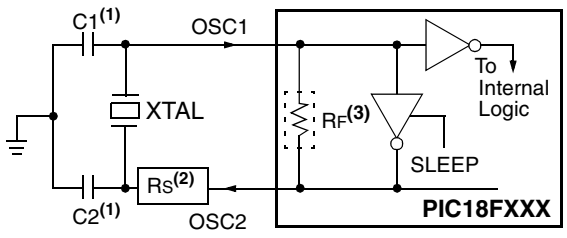
2.2 Crystal Oscillator/Ceramic Resonators

In XT, LP, HS or HS+PLL Oscillator modes, a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation. Figure 2-1 shows the pin connections.

The PIC18FXX2 oscillator design requires the use of a parallel cut crystal.

Note:	Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications.

FIGURE 2-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP CONFIGURATION)



Note 1: See Table 2-1 and Table 2-2 for recommended values of C1 and C2.

2: A series resistor (RS) may be required for AT strip cut crystals.

3: RF varies with the Oscillator mode chosen.

TABLE 2-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq**	**C1**	**C2**
XT	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF
These values are for design guidance only. See notes following this table.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B	± 0.3%	
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%	
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%	
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%	
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%	
All resonators used did not have built-in capacitors.			

Note 1: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.

2: When operating below 3V VDD, or when using certain ceramic resonators at any voltage, it may be necessary to use high-gain HS mode, try a lower frequency resonator, or switch to a crystal oscillator.

3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components, or verify oscillator performance.

2.7 Effects of SLEEP Mode on the On-Chip Oscillator

When the device executes a SLEEP instruction, the on-chip clocks and oscillator are turned off and the device is held at the beginning of an instruction cycle (Q1 state). With the oscillator off, the OSC1 and OSC2 signals will stop oscillating. Since all the transistor switching currents have been removed, SLEEP mode achieves the lowest current consumption of the device (only leakage currents). Enabling any on-chip feature that will operate during SLEEP will increase the current consumed during SLEEP. The user can wake from SLEEP through external RESET, Watchdog Timer Reset, or through an interrupt.

TABLE 2-3: OSC1 AND OSC2 PIN STATES IN SLEEP MODE

OSC Mode	OSC1 Pin	OSC2 Pin
RC	Floating, external resistor should pull high	At logic low
RCIO	Floating, external resistor should pull high	Configured as PORTA, bit 6
ECIO	Floating	Configured as PORTA, bit 6
EC	Floating	At logic low
LP, XT, and HS	Feedback inverter disabled, at quiescent voltage level	Feedback inverter disabled, at quiescent voltage level

Note: See Table 3-1, in the **"Reset"** section, for time-outs due to SLEEP and $\overline{\text{MCLR}}$ Reset.

2.8 Power-up Delays

Power up delays are controlled by two timers, so that no external RESET circuitry is required for most applications. The delays ensure that the device is kept in RESET, until the device power supply and clock are stable. For additional information on RESET operation, see Section 3.0.

The first timer is the Power-up Timer (PWRT), which optionally provides a fixed delay of 72 ms (nominal) on power-up only (POR and BOR). The second timer is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable.

With the PLL enabled (HS/PLL Oscillator mode), the time-out sequence following a Power-on Reset is different from other Oscillator modes. The time-out sequence is as follows: First, the PWRT time-out is invoked after a POR time delay has expired. Then, the Oscillator Start-up Timer (OST) is invoked. However, this is still not a sufficient amount of time to allow the PLL to lock at high frequencies. The PWRT timer is used to provide an additional fixed 2 ms (nominal) time-out to allow the PLL ample time to lock to the incoming clock frequency.

TABLE 3-1: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up[2]		Brown-out	Wake-up from SLEEP or Oscillator Switch
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1		
HS with PLL enabled[1]	72 ms + 1024 TOSC + 2ms	1024 TOSC + 2 ms	72 ms[2] + 1024 TOSC + 2 ms	1024 TOSC + 2 ms
HS, XT, LP	72 ms + 1024 TOSC	1024 TOSC	72 ms[2] + 1024 TOSC	1024 TOSC
EC	72 ms	—	72 ms[2]	—
External RC	72 ms	—	72 ms[2]	—

Note 1: 2 ms is the nominal time required for the 4x PLL to lock.
2: 72 ms is the nominal power-up timer delay, if implemented.

REGISTER 3-1: RCON REGISTER BITS AND POSITIONS

R/W-0	U-0	U-0	R/W-1	R-1	R-1	R/W-0	R/W-0
IPEN	—	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Note 1: Refer to Section 4.14 (page 53) for bit definitions.

TABLE 3-2: STATUS BITS, THEIR SIGNIFICANCE AND THE INITIALIZATION CONDITION FOR RCON REGISTER

Condition	Program Counter	RCON Register	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	STKFUL	STKUNF
Power-on Reset	0000h	0--1 1100	1	1	1	0	0	u	u
$\overline{MCLR}$ Reset during normal operation	0000h	0--u uuuu	u	u	u	u	u	u	u
Software Reset during normal operation	0000h	0--0 uuuu	0	u	u	u	u	u	u
Stack Full Reset during normal operation	0000h	0--u uu11	u	u	u	u	u	u	1
Stack Underflow Reset during normal operation	0000h	0--u uu11	u	u	u	u	u	1	u
$\overline{MCLR}$ Reset during SLEEP	0000h	0--u 10uu	u	1	0	u	u	u	u
WDT Reset	0000h	0--u 01uu	1	0	1	u	u	u	u
WDT Wake-up	PC + 2	u--u 00uu	u	0	0	u	u	u	u
Brown-out Reset	0000h	0--1 11u0	1	1	1	1	0	u	u
Interrupt wake-up from SLEEP	PC + 2[1]	u--u 00uu	u	1	0	u	u	u	u

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0'

Note 1: When the wake-up is due to an interrupt and the GIEH or GIEL bits are set, the PC is loaded with the interrupt vector (0x000008h or 0x000018h).

TABLE 3-3: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices				Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets WDT Reset RESET Instruction Stack Resets	Wake-up via WDT or Interrupt
ADRESH	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADRESL	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	242	442	252	452	0000 00-0	0000 00-0	uuuu uu-u
ADCON1	242	442	252	452	00-- 0000	00-- 0000	uu-- uuuu
CCPR1H	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1L	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	242	442	252	452	--00 0000	--00 0000	--uu uuuu
CCPR2H	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR2L	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	242	442	252	452	--00 0000	--00 0000	--uu uuuu
TMR3H	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR3L	242	442	252	452	xxxx xxxx	uuuu uuuu	uuuu uuuu
T3CON	242	442	252	452	0000 0000	uuuu uuuu	uuuu uuuu
SPBRG	242	442	252	452	0000 0000	0000 0000	uuuu uuuu
RCREG	242	442	252	452	0000 0000	0000 0000	uuuu uuuu
TXREG	242	442	252	452	0000 0000	0000 0000	uuuu uuuu
TXSTA	242	442	252	452	0000 -010	0000 -010	uuuu -uuu
RCSTA	242	442	252	452	0000 000x	0000 000x	uuuu uuuu
EEADR	242	442	252	452	0000 0000	0000 0000	uuuu uuuu
EEDATA	242	442	252	452	0000 0000	0000 0000	uuuu uuuu
EECON1	242	442	252	452	xx-0 x000	uu-0 u000	uu-0 u000
EECON2	242	442	252	452	---- ----	---- ----	---- ----

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition.
Shaded cells indicate conditions do not apply for the designated device.

Note 1: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

4: See Table 3-2 for RESET value for specific condition.

5: Bit 6 of PORTA, LATA, and TRISA are enabled in ECIO and RCIO Oscillator modes only. In all other Oscillator modes, they are disabled and read ’0’.

6: Bit 6 of PORTA, LATA and TRISA are not available on all devices. When unimplemented, they are read ’0’.

4.10 Access Bank

The Access Bank is an architectural enhancement which is very useful for C compiler code optimization. The techniques used by the C compiler may also be useful for programs written in assembly.

This data memory region can be used for:

- Intermediate computational values
- Local variables of subroutines
- Faster context saving/switching of variables
- Common variables
- Faster evaluation/control of SFRs (no banking)

The Access Bank is comprised of the upper 128 bytes in Bank 15 (SFRs) and the lower 128 bytes in Bank 0. These two sections will be referred to as Access RAM High and Access RAM Low, respectively. Figure 4-6 and Figure 4-7 indicate the Access RAM areas.

A bit in the instruction word specifies if the operation is to occur in the bank specified by the BSR register or in the Access Bank. This bit is denoted by the 'a' bit (for access bit).

When forced in the Access Bank (a = 0), the last address in Access RAM Low is followed by the first address in Access RAM High. Access RAM High maps the Special Function registers, so that these registers can be accessed without any software overhead. This is useful for testing status flags and modifying control bits.

4.11 Bank Select Register (BSR)

The need for a large general purpose memory space dictates a RAM banking scheme. The data memory is partitioned into sixteen banks. When using direct addressing, the BSR should be configured for the desired bank.

BSR<3:0> holds the upper 4 bits of the 12-bit RAM address. The BSR<7:4> bits will always read '0's, and writes will have no effect.

A `MOVLB` instruction has been provided in the instruction set to assist in selecting banks.

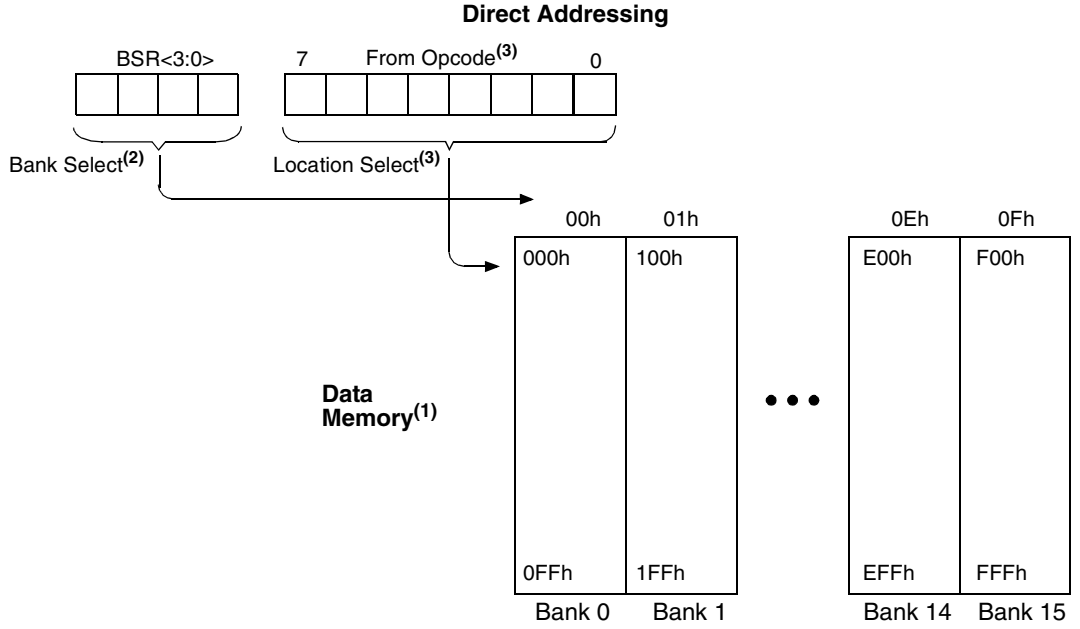
If the currently selected bank is not implemented, any read will return all '0's and all writes are ignored. The STATUS register bits will be set/cleared as appropriate for the instruction performed.

Each Bank extends up to FFh (256 bytes). All data memory is implemented as static RAM.

A `MOVFF` instruction ignores the BSR, since the 12-bit addresses are embedded into the instruction word.

Section 4.12 provides a description of indirect addressing, which allows linear addressing of the entire RAM space.

FIGURE 4-8: DIRECT ADDRESSING



Note 1: For register file map detail, see Table 4-1.

2: The access bit of the instruction can be used to force an override of the selected bank (BSR<3:0>) to the registers of the Access Bank.

3: The `MOVFF` instruction embeds the entire 12-bit address in the instruction.

EXAMPLE 5-3: WRITING TO FLASH PROGRAM MEMORY

```
            MOVLW   D'64                        ; number of bytes in erase block
            MOVWF   COUNTER
            MOVLW   BUFFER_ADDR_HIGH            ; point to buffer
            MOVWF   FSR0H
            MOVLW   BUFFER_ADDR_LOW
            MOVWF   FSR0L
            MOVLW   CODE_ADDR_UPPER             ; Load TBLPTR with the base
            MOVWF   TBLPTRU                     ; address of the memory block
            MOVLW   CODE_ADDR_HIGH
            MOVWF   TBLPTRH
            MOVLW   CODE_ADDR_LOW
            MOVWF   TBLPTRL
READ_BLOCK
            TBLRD*+                             ; read into TABLAT, and inc
            MOVF    TABLAT, W                   ; get data
            MOVWF   POSTINC0                    ; store data
            DECFSZ  COUNTER                     ; done?
            BRA     READ_BLOCK                  ; repeat
MODIFY_WORD
            MOVLW   DATA_ADDR_HIGH              ; point to buffer
            MOVWF   FSR0H
            MOVLW   DATA_ADDR_LOW
            MOVWF   FSR0L
            MOVLW   NEW_DATA_LOW                ; update buffer word
            MOVWF   POSTINC0
            MOVLW   NEW_DATA_HIGH
            MOVWF   INDF0
ERASE_BLOCK
            MOVLW   CODE_ADDR_UPPER             ; load TBLPTR with the base
            MOVWF   TBLPTRU                     ; address of the memory block
            MOVLW   CODE_ADDR_HIGH
            MOVWF   TBLPTRH
            MOVLW   CODE_ADDR_LOW
            MOVWF   TBLPTRL
            BSF     EECON1,EEPGD                ; point to FLASH program memory
            BCF     EECON1,CFGS                 ; access FLASH program memory
            BSF     EECON1,WREN                 ; enable write to memory
            BSF     EECON1,FREE                 ; enable Row Erase operation
            BCF     INTCON,GIE                  ; disable interrupts
            MOVLW   55h
            MOVWF   EECON2                      ; write 55h
            MOVLW   AAh
            MOVWF   EECON2                      ; write AAh
            BSF     EECON1,WR                   ; start erase (CPU stall)
            BSF     INTCON,GIE                  ; re-enable interrupts
            TBLRD*-                             ; dummy read decrement
WRITE_BUFFER_BACK
            MOVLW   8                           ; number of write buffer groups of 8 bytes
            MOVWF   COUNTER_HI
            MOVLW   BUFFER_ADDR_HIGH            ; point to buffer
            MOVWF   FSR0H
            MOVLW   BUFFER_ADDR_LOW
            MOVWF   FSR0L
PROGRAM_LOOP
            MOVLW   8                           ; number of bytes in holding register
            MOVWF   COUNTER
WRITE_WORD_TO_HREGS
            MOVF    POSTINC0, W                 ; get low byte of buffer data
            MOVWF   TABLAT                      ; present data to table latch
            TBLWT+*                             ; write data, perform a short write
                                                ; to internal TBLWT holding register.
            DECFSZ  COUNTER                     ; loop until buffers are full
            BRA     WRITE_WORD_TO_HREGS
```

8.1 INTCON Registers

The INTCON Registers are readable and writable registers, which contain various enable, priority and flag bits.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

REGISTER 8-1: INTCON REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF
bit 7							bit 0

bit 7 **GIE/GIEH:** Global Interrupt Enable bit

When IPEN = 0:
1 = Enables all unmasked interrupts
0 = Disables all interrupts

When IPEN = 1:
1 = Enables all high priority interrupts
0 = Disables all interrupts

bit 6 **PEIE/GIEL:** Peripheral Interrupt Enable bit

When IPEN = 0:
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

When IPEN = 1:
1 = Enables all low priority peripheral interrupts
0 = Disables all low priority peripheral interrupts

bit 5 **TMR0IE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 overflow interrupt
0 = Disables the TMR0 overflow interrupt

bit 4 **INT0IE:** INT0 External Interrupt Enable bit
1 = Enables the INT0 external interrupt
0 = Disables the INT0 external interrupt

bit 3 **RBIE:** RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **TMR0IF:** TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INT0IF:** INT0 External Interrupt Flag bit
1 = The INT0 external interrupt occurred (must be cleared in software)
0 = The INT0 external interrupt did not occur

bit 0 **RBIF:** RB Port Change Interrupt Flag bit
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

Note: A mismatch condition will continue to set this bit. Reading PORTB will end the mismatch condition and allow the bit to be cleared.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

NOTES:

9.0 I/O PORTS

Depending on the device selected, there are either five ports or three ports available. Some pins of the I/O ports are multiplexed with an alternate function from the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Each port has three registers for its operation. These registers are:

- TRIS register (data direction register)
- PORT register (reads the levels on the pins of the device)
- LAT register (output latch)

The data latch (LAT register) is useful for read-modify-write operations on the value that the I/O pins are driving.

9.1 PORTA, TRISA and LATA Registers

PORTA is a 7-bit wide, bi-directional port. The corresponding Data Direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., put the contents of the output latch on the selected pin).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch.

The Data Latch register (LATA) is also memory mapped. Read-modify-write operations on the LATA register reads and writes the latched output value for PORTA.

The RA4 pin is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers.

The other PORTA pins are multiplexed with analog inputs and the analog VREF+ and VREF- inputs. The operation of each pin is selected by clearing/setting the control bits in the ADCON1 register (A/D Control Register1).

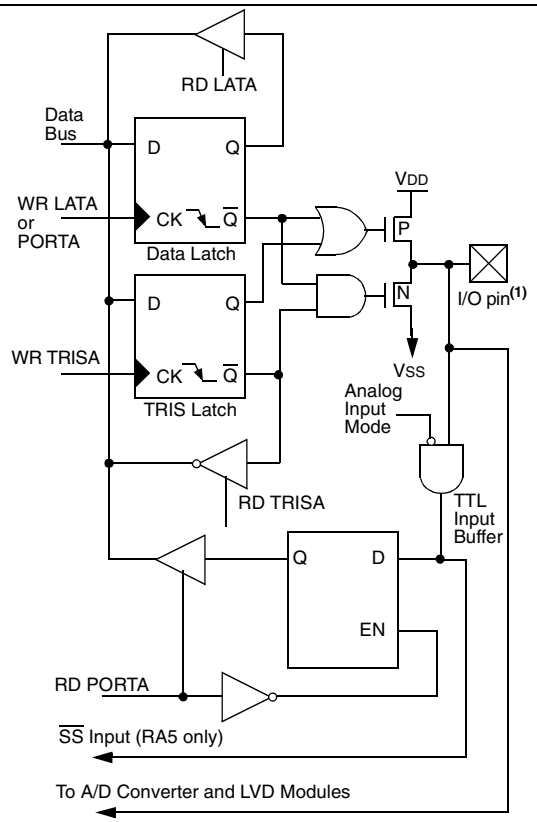
Note:	On a Power-on Reset, RA5 and RA3:RA0 are configured as analog inputs and read as '0'. RA6 and RA4 are configured as digital inputs.

The TRISA register controls the direction of the RA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

EXAMPLE 9-1: INITIALIZING PORTA

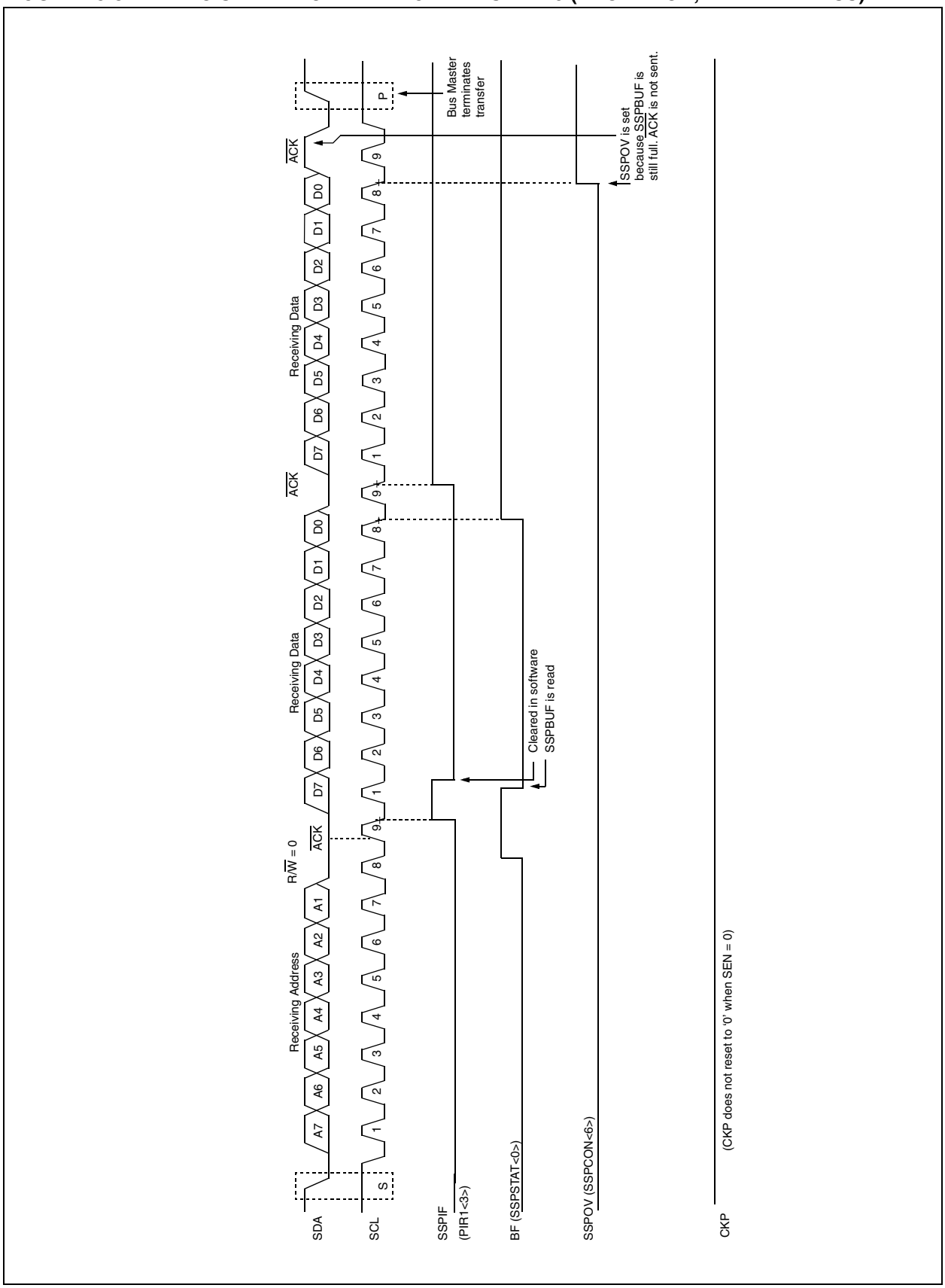
```
CLRF PORTA      ; Initialize PORTA by
                ; clearing output
                ; data latches
CLRF LATA       ; Alternate method
                ; to clear output
                ; data latches
MOVLW 0x07      ; Configure A/D
MOVWF ADCON1    ; for digital inputs
MOVLW 0xCF      ; Value used to
                ; initialize data
                ; direction
MOVWF TRISA     ; Set RA<3:0> as inputs
                ; RA<5:4> as outputs
```

FIGURE 9-1: BLOCK DIAGRAM OF RA3:RA0 AND RA5 PINS



Note 1: I/O pins have protection diodes to VDD and VSS.

FIGURE 15-8: I^2C SLAVE MODE TIMING WITH SEN = 0 (RECEPTION, 7-BIT ADDRESS)



15.4.4 CLOCK STRETCHING

Both 7- and 10-bit Slave modes implement automatic clock stretching during a transmit sequence.

The SEN bit (SSPCON2<0>) allows clock stretching to be enabled during receives. Setting SEN will cause the SCL pin to be held low at the end of each data receive sequence.

15.4.4.1 Clock Stretching for 7-bit Slave Receive Mode (SEN = 1)

In 7-bit Slave Receive mode, on the falling edge of the ninth clock at the end of the $\overline{ACK}$ sequence, if the BF bit is set, the CKP bit in the SSPCON1 register is automatically cleared, forcing the SCL output to be held low. The CKP being cleared to '0' will assert the SCL line low. The CKP bit must be set in the user's ISR before reception is allowed to continue. By holding the SCL line low, the user has time to service the ISR and read the contents of the SSPBUF before the master device can initiate another receive sequence. This will prevent buffer overruns from occurring (see Figure 15-13).

Note 1: If the user reads the contents of the SSPBUF before the falling edge of the ninth clock, thus clearing the BF bit, the CKP bit will not be cleared and clock stretching will not occur.

2: The CKP bit can be set in software, regardless of the state of the BF bit. The user should be careful to clear the BF bit in the ISR before the next receive sequence, in order to prevent an overflow condition.

15.4.4.2 Clock Stretching for 10-bit Slave Receive Mode (SEN = 1)

In 10-bit Slave Receive mode, during the address sequence, clock stretching automatically takes place but CKP is not cleared. During this time, if the UA bit is set after the ninth clock, clock stretching is initiated. The UA bit is set after receiving the upper byte of the 10-bit address, and following the receive of the second byte of the 10-bit address with the R/$\overline{W}$ bit cleared to '0'. The release of the clock line occurs upon updating SSPADD. Clock stretching will occur on each data receive sequence as described in 7-bit mode.

Note: If the user polls the UA bit and clears it by updating the SSPADD register before the falling edge of the ninth clock occurs, and if the user hasn't cleared the BF bit by reading the SSPBUF register before that time, then the CKP bit will still NOT be asserted low. Clock stretching on the basis of the state of the BF bit only occurs during a data sequence, not an address sequence.

15.4.4.3 Clock Stretching for 7-bit Slave Transmit Mode

7-bit Slave Transmit mode implements clock stretching by clearing the CKP bit after the falling edge of the ninth clock, if the BF bit is clear. This occurs, regardless of the state of the SEN bit.

The user's ISR must set the CKP bit before transmission is allowed to continue. By holding the SCL line low, the user has time to service the ISR and load the contents of the SSPBUF before the master device can initiate another transmit sequence (see Figure 15-9).

Note 1: If the user loads the contents of SSPBUF, setting the BF bit before the falling edge of the ninth clock, the CKP bit will not be cleared and clock stretching will not occur.

2: The CKP bit can be set in software, regardless of the state of the BF bit.

15.4.4.4 Clock Stretching for 10-bit Slave Transmit Mode

In 10-bit Slave Transmit mode, clock stretching is controlled during the first two address sequences by the state of the UA bit, just as it is in 10-bit Slave Receive mode. The first two addresses are followed by a third address sequence, which contains the high order bits of the 10-bit address and the R/$\overline{W}$ bit set to '1'. After the third address sequence is performed, the UA bit is not set, the module is now configured in Transmit mode, and clock stretching is controlled by the BF flag, as in 7-bit Slave Transmit mode (see Figure 15-11).

15.4.8 I²C MASTER MODE START CONDITION TIMING

To initiate a START condition, the user sets the START condition enable bit, SEN (SSPCON2<0>). If the SDA and SCL pins are sampled high, the baud rate generator is reloaded with the contents of SSPADD<6:0> and starts its count. If SCL and SDA are both sampled high when the baud rate generator times out (TBRG), the SDA pin is driven low. The action of the SDA being driven low, while SCL is high, is the START condition and causes the S bit (SSPSTAT<3>) to be set. Following this, the baud rate generator is reloaded with the contents of SSPADD<6:0> and resumes its count. When the baud rate generator times out (TBRG), the SEN bit (SSPCON2<0>) will be automatically cleared by hardware, the baud rate generator is suspended, leaving the SDA line held low and the START condition is complete.

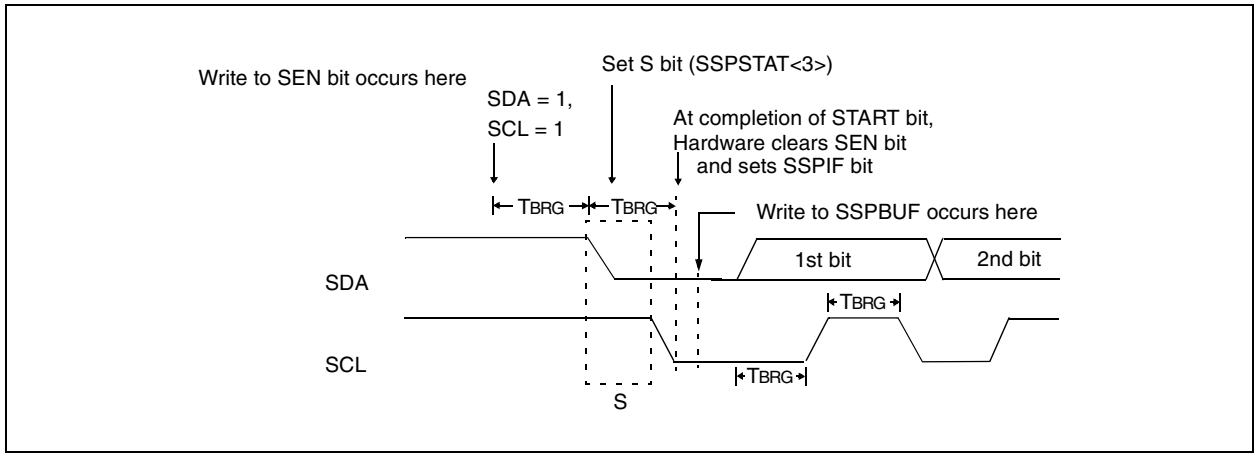
Note:	If at the beginning of the START condition, the SDA and SCL pins are already sampled low, or if during the START condition the SCL line is sampled low before the SDA line is driven low, a bus collision occurs, the Bus Collision Interrupt Flag, BCLIF is set, the START condition is aborted, and the I²C module is reset into its IDLE state.

15.4.8.1 WCOL Status Flag

If the user writes the SSPBUF when a START sequence is in progress, the WCOL is set and the contents of the buffer are unchanged (the write doesn't occur).

Note:	Because queueing of events is not allowed, writing to the lower 5 bits of SSPCON2 is disabled until the START condition is complete.

FIGURE 15-19: FIRST START BIT TIMING



REGISTER 17-2: ADCON1 REGISTER

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	ADCS2	—	—	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified. Six (6) Most Significant bits of ADRESH are read as '0'.
0 = Left justified. Six (6) Least Significant bits of ADRESL are read as '0'.

bit 6 **ADCS2:** A/D Conversion Clock Select bit (ADCON1 bits in **bold**)

ADCON1 <ADCS2>	ADCON0 <ADCS1:ADCS0>	Clock Conversion
0	00	FOSC/2
0	01	FOSC/8
0	10	FOSC/32
0	11	FRC (clock derived from the internal A/D RC oscillator)
1	00	FOSC/4
1	01	FOSC/16
1	10	FOSC/64
1	11	FRC (clock derived from the internal A/D RC oscillator)

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **PCFG3:PCFG0:** A/D Port Configuration Control bits

PCFG <3:0>	AN7	AN6	AN5	AN4	AN3	AN2	AN1	AN0	VREF+	VREF-	C / R
0000	A	A	A	A	A	A	A	A	VDD	VSS	8 / 0
0001	A	A	A	A	VREF+	A	A	A	AN3	VSS	7 / 1
0010	D	D	D	A	A	A	A	A	VDD	VSS	5 / 0
0011	D	D	D	A	VREF+	A	A	A	AN3	VSS	4 / 1
0100	D	D	D	D	A	D	A	A	VDD	VSS	3 / 0
0101	D	D	D	D	VREF+	D	A	A	AN3	VSS	2 / 1
011x	D	D	D	D	D	D	D	D	—	—	0 / 0
1000	A	A	A	A	VREF+	VREF-	A	A	AN3	AN2	6 / 2
1001	D	D	A	A	A	A	A	A	VDD	VSS	6 / 0
1010	D	D	A	A	VREF+	A	A	A	AN3	VSS	5 / 1
1011	D	D	A	A	VREF+	VREF-	A	A	AN3	AN2	4 / 2
1100	D	D	D	A	VREF+	VREF-	A	A	AN3	AN2	3 / 2
1101	D	D	D	D	VREF+	VREF-	A	A	AN3	AN2	2 / 2
1110	D	D	D	D	D	D	D	A	VDD	VSS	1 / 0
1111	D	D	D	D	VREF+	VREF-	D	A	AN3	AN2	1 / 2

A = Analog input D = Digital I/O
C/R = # of analog input channels / # of A/D voltage references

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

Note: On any device RESET, the port pins that are multiplexed with analog functions (ANx) are forced to be an analog input.

17.5 Use of the CCP2 Trigger

An A/D conversion can be started by the "special event trigger" of the CCP2 module. This requires that the CCP2M3:CCP2M0 bits (CCP2CON<3:0>) be programmed as 1011 and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH/ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition done before the "special event trigger" sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the "special event trigger" will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

TABLE 17-2: SUMMARY OF A/D REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
INTCON	GIE/ GIEH	PEIE/ GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	0000 0000	0000 0000
PIR2	—	—	—	EEIF	BCLIF	LVDIF	TMR3IF	CCP2IF	---0 0000	---0 0000
PIE2	—	—	—	EEIE	BCLIE	LVDIE	TMR3IE	CCP2IE	---0 0000	---0 0000
IPR2	—	—	—	EEIP	BCLIP	LVDIP	TMR3IP	CCP2IP	---1 1111	---1 0000
ADRESH	A/D Result Register								xxxx xxxx	uuuu uuuu
ADRESL	A/D Result Register								xxxx xxxx	uuuu uuuu
ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON	0000 00-0	0000 00-0
ADCON1	ADFM	ADCS2	—	—	PCFG3	PCFG2	PCFG1	PCFG0	---- -000	---- -000
PORTA	—	RA6	RA5	RA4	RA3	RA2	RA1	RA0	--0x 0000	--0u 0000
TRISA	—	PORTA Data Direction Register							--11 1111	--11 1111
PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -000	---- -000
LATE	—	—	—	—	—	LATE2	LATE1	LATE0	---- -xxx	---- -uuu
TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction bits			0000 -111	0000 -111

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18F2X2 devices; always maintain these bits clear.

REGISTER 19-8: CONFIGURATION REGISTER 6 LOW (CONFIG6L: BYTE ADDRESS 30000Ah)

U-0	U-0	U-0	U-0	R/C-1	R/C-1	R/C-1	R/C-1
—	—	—	—	WRT3(1)	WRT2(1)	WRT1	WRT0
bit 7							bit 0

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **WRT3:** Write Protection bit(1)
1 = Block 3 (006000-007FFFh) not write protected
0 = Block 3 (006000-007FFFh) write protected

bit 2 **WRT2:** Write Protection bit(1)
1 = Block 2 (004000-005FFFh) not write protected
0 = Block 2 (004000-005FFFh) write protected

bit 1 **WRT1:** Write Protection bit
1 = Block 1 (002000-003FFFh) not write protected
0 = Block 1 (002000-003FFFh) write protected

bit 0 **WRT0:** Write Protection bit
1 = Block 0 (000200h-001FFFh) not write protected
0 = Block 0 (000200h-001FFFh) write protected

Note 1: Unimplemented in PIC18FX42 devices; maintain this bit set.

Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed		u = Unchanged from programmed state

REGISTER 19-9: CONFIGURATION REGISTER 6 HIGH (CONFIG6H: BYTE ADDRESS 30000Bh)

R/C-1	R/C-1	C-1	U-0	U-0	U-0	U-0	U-0
WRTD	WRTB	WRTC	—	—	—	—	—
bit 7							bit 0

bit 7 **WRTD:** Data EEPROM Write Protection bit
1 = Data EEPROM not write protected
0 = Data EEPROM write protected

bit 6 **WRTB:** Boot Block Write Protection bit
1 = Boot Block (000000-0001FFh) not write protected
0 = Boot Block (000000-0001FFh) write protected

bit 5 **WRTC:** Configuration Register Write Protection bit
1 = Configuration registers (300000-3000FFh) not write protected
0 = Configuration registers (300000-3000FFh) write protected

Note: This bit is read only, and cannot be changed in User mode.

bit 4-0 **Unimplemented:** Read as '0'

Legend:		
R = Readable bit	C =Clearable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed		u = Unchanged from programmed state

22.1 DC Characteristics: PIC18FXX2 (Industrial, Extended) PIC18LFXX2 (Industrial) (Continued)

PIC18LFXX2 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18FXX2 (Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	IDD	**Supply Current(2,4) (Continued)**					
D010C		PIC18LFXX2	—	10	25	mA	EC, ECIO osc configurations VDD = 4.2V, -40°C to +85°C
D010C		PIC18FXX2	—	10	25	mA	EC, ECIO osc configurations VDD = 4.2V, -40°C to +125°C
D013		PIC18LFXX2	—	.6	2	mA	HS osc configuration FOSC = 4 MHz, VDD = 2.0V
			—	10	15	mA	FOSC = 25 MHz, VDD = 5.5V HS + PLL osc configurations
			—	15	25	mA	FOSC = 10 MHz, VDD = 5.5V
D013		PIC18FXX2	—	10	15	mA	HS osc configuration FOSC = 25 MHz, VDD = 5.5V HS + PLL osc configurations
			—	15	25	mA	FOSC = 10 MHz, VDD = 5.5V
D014		PIC18LFXX2	—	15	55	µA	Timer1 osc configuration FOSC = 32 kHz, VDD = 2.0V
D014		PIC18FXX2	—	—	200	µA	Timer1 osc configuration FOSC = 32 kHz, VDD = 4.2V, -40°C to +85°C
			—	—	250	µA	FOSC = 32 kHz, VDD = 4.2V, -40°C to +125°C
	IPD	**Power-down Current(3)**					
D020		PIC18LFXX2	—	.08	.9	µA	VDD = 2.0V, +25°C
			—	.1	4	µA	VDD = 2.0V, -40°C to +85°C
			—	3	10	µA	VDD = 4.2V, -40°C to +85°C
D020		PIC18FXX2	—	.1	.9	µA	VDD = 4.2V, +25°C
			—	3	10	µA	VDD = 4.2V, -40°C to +85°C
D021B			—	15	25	µA	VDD = 4.2V, -40°C to +125°C

Legend: Shading of rows is to assist in readability of the table.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode, or during a device RESET, without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active Operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR,...).

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: The LVD and BOR modules share a large portion of circuitry. The ΔIBOR and ΔILVD currents are not additive. Once one of these modules is enabled, the other may also be enabled without further penalty.

FIGURE 23-3: TYPICAL IDD vs. FOSC OVER VDD (HS/PLL MODE)

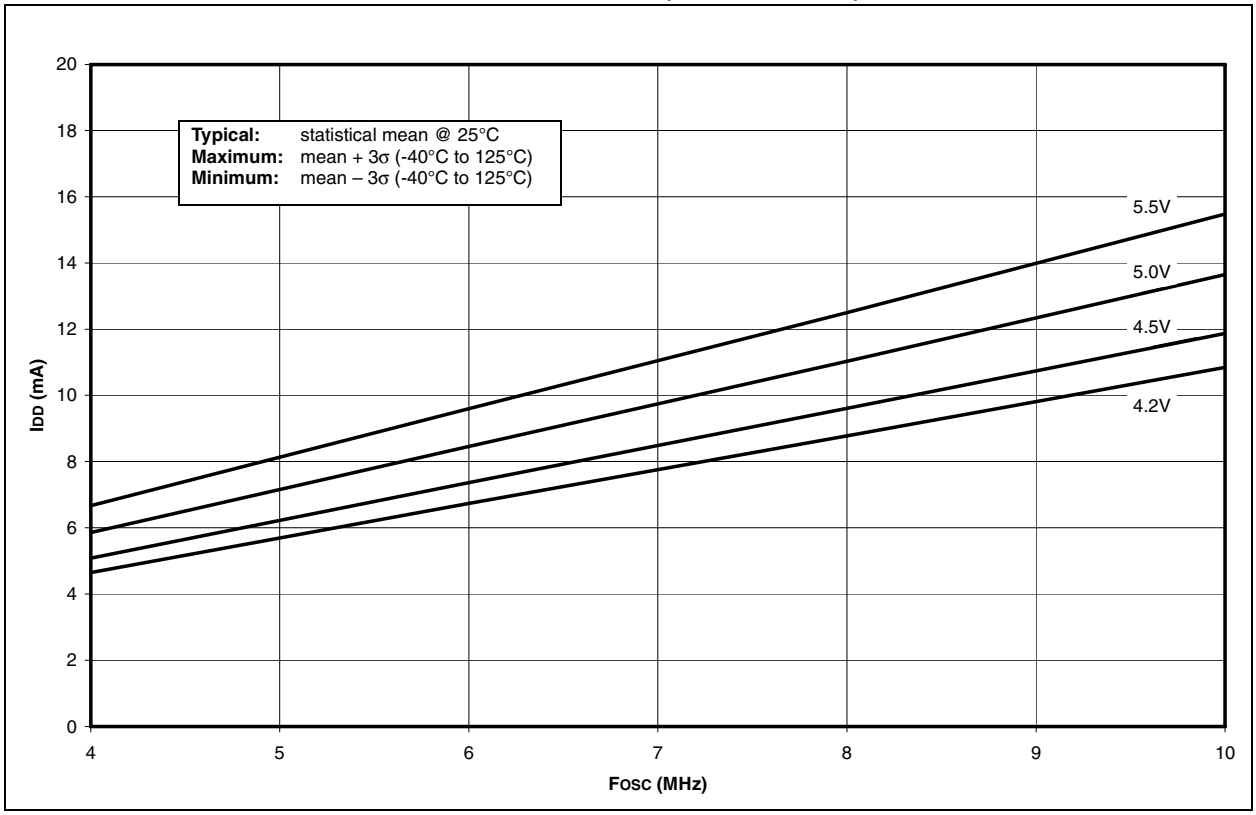
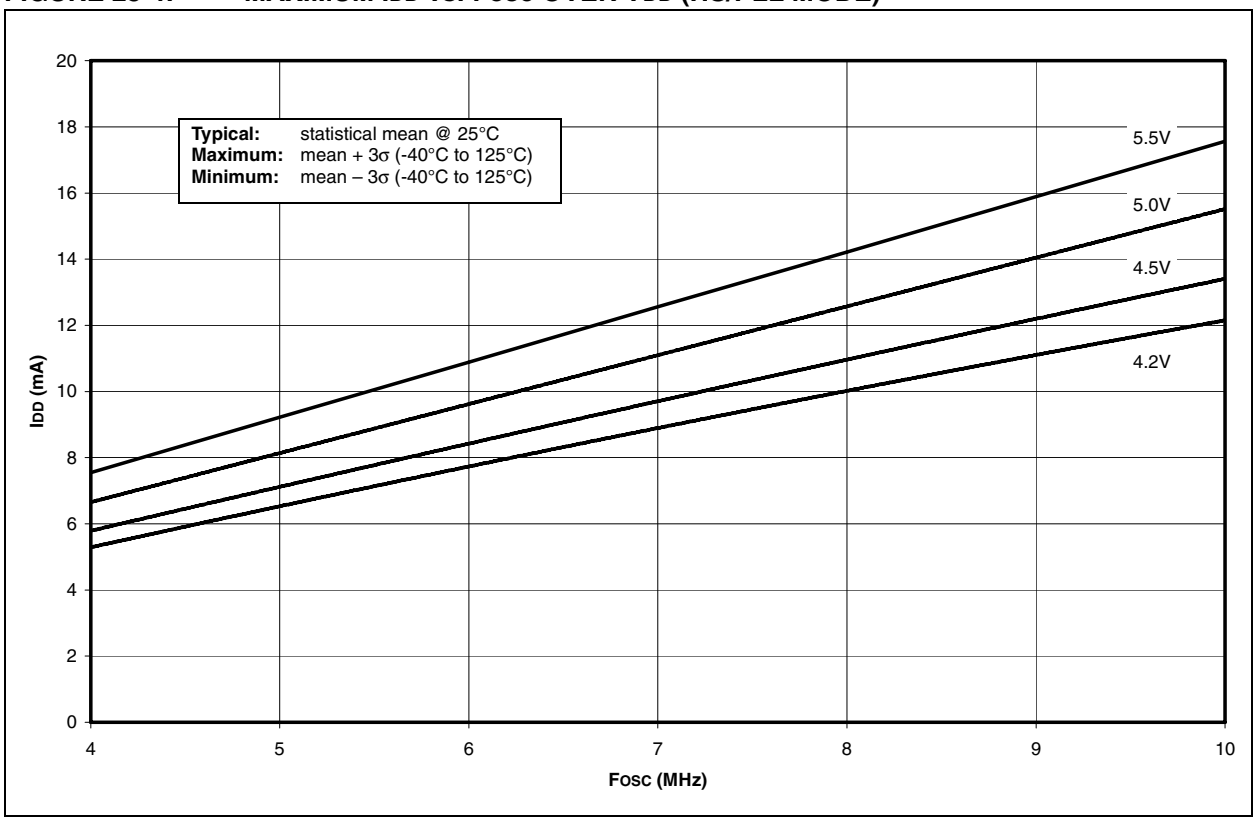


FIGURE 23-4: MAXIMUM IDD vs. FOSC OVER VDD (HS/PLL MODE)



NOTES:

PIC18FXX2 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	–	X	/XX	XXX
Device		Temperature Range	Package	Pattern

Device	PIC18FXX2(1), PIC18FXX2T(2); VDD range 4.2V to 5.5V PIC18LFXX2(1), PIC18LFXX2T(2); VDD range 2.5V to 5.5V
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	PT = TQFP (Thin Quad Flatpack) SO = SOIC SP = Skinny Plastic DIP P = PDIP L = PLCC
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC18LF452 - I/P 301 = Industrial temp., PDIP package, Extended VDD limits, QTP pattern #301.

b) PIC18LF242 - I/SO = Industrial temp., SOIC package, Extended VDD limits.

c) PIC18F442 - E/P = Extended temp., PDIP package, normal VDD limits.

Note 1: F = Standard Voltage range
LF = Wide Voltage Range

2: T = in tape and reel - SOIC, PLCC, and TQFP packages only.